

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220J – JULY 1998 – REVISED FEBRUARY 2004

- Rail-to-Rail Output Swing
- Gain Bandwidth Product . . . 6.4 MHz
- $\pm 80$  mA Output Drive Capability
- Supply Current . . . 500  $\mu$ A/channel
- Input Offset Voltage . . . 100  $\mu$ V
- Input Noise Voltage . . . 11 nV/ $\sqrt{\text{Hz}}$
- Slew Rate . . . 1.6 V/ $\mu$ s
- Micropower Shutdown Mode (TLV2460/3/5) . . . 0.3  $\mu$ A/Channel
- Universal Operational Amplifier EVM
- Available in Q-Temp Automotive HighRel Automotive Applications Configuration Control/Print Support Qualification to Automotive Standards



### description

The TLV246x is a family of low-power rail-to-rail input/output operational amplifiers specifically designed for portable applications. The input common-mode voltage range extends beyond the supply rails for maximum dynamic range in low-voltage systems. The amplifier output has rail-to-rail performance with high-output-drive capability, solving one of the limitations of older rail-to-rail input/output operational amplifiers. This rail-to-rail dynamic range and high output drive make the TLV246x ideal for buffering analog-to-digital converters.

The operational amplifier has 6.4 MHz of bandwidth and 1.6 V/ $\mu$ s of slew rate with only 500  $\mu$ A of supply current, providing good ac performance with low power consumption. Three members of the family offer a shutdown terminal, which places the amplifier in an ultralow supply current mode ( $I_{DD} = 0.3 \mu\text{A}/\text{ch}$ ). While in shutdown, the operational-amplifier output is placed in a high-impedance state. DC applications are also well served with an input noise voltage of 11 nV/ $\sqrt{\text{Hz}}$  and input offset voltage of 100  $\mu$ V.

This family is available in the low-profile SOT23, MSOP, and TSSOP packages. The TLV2460 is the first rail-to-rail input/output operational amplifier with shutdown available in the 6-pin SOT23, making it perfect for high-density circuits. The family is specified over an expanded temperature range ( $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ) for use in industrial control and automotive systems, and over the military temperature range ( $T_A = -55^\circ\text{C}$  to  $125^\circ\text{C}$ ) for use in military systems.

### SELECTION GUIDE

DEVICE	V <sub>DD</sub> [V]	V <sub>IO</sub> [ $\mu$ V]	I <sub>DD</sub> /ch [ $\mu$ A]	I <sub>IB</sub> [pA]	GBW [MHz]	SLEW RATE [V/ $\mu$ s]	V <sub>n</sub> , 1 kHz [nV/ $\sqrt{\text{Hz}}$ ]	I <sub>O</sub> [mA]	SHUTDOWN	RAIL-RAIL
TLV246x(A)	2.7–6	150	550	1300	6.4	1.6	11	25	Y	I/O
TLV277x(A)	2.5–5.5	360	1000	2	5.1	10.5	17	6	Y	O
TLV247x(A)	2.7–6	250	600	2.5	2.8	1.5	15	20	Y	I/O
TLV245x(A)	2.7–6	20	23	500	0.22	0.11	52	10	Y	I/O
TLV225x(A)	2.7–8	200	35	1	0.2	0.12	19	3	—	—
TLV226x(A)	2.7–8	300	200	1	0.71	0.55	12	3	—	—



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### TLV2460C//AI and TLV2461C//AI AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IOmax</sub> AT 25°C	PACKAGED DEVICES			
		SMALL OUTLINE (D)	SOT-23† (DBV)	SYMBOL	PLASTIC DIP (P)
0°C to 70°C	2000 μV	TLV2460CD TLV2461CD	TLV2460CDBV TLV2461CDBV	VAOC VAPC	TLV2460CP TLV2461CP
-40°C to 125°C	2000 μV	TLV2460ID TLV2461ID	TLV2460IDBV TLV2461IDBV	VAOI VAPI	TLV2460IP TLV2461IP
	1500 μV	TLV2460AID TLV2461AID	— —	— —	TLV2460AIP TLV2461AIP

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2460CDR).

‡ Chip forms are tested at T<sub>A</sub> = 25°C only.

### TLV2460M//AM//Q//AQ and TLV2461M//AM//Q//AQ AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IOmax</sub> AT 25°C	PACKAGED DEVICES				
		SMALL OUTLINE† (D)	SMALL OUTLINE† (PW)	CERAMIC DIP (JG)	CERAMIC FLATPACK (U)	CHIP CARRIER (FK)
-40°C to 125°C	2000 μV	TLV2460QD TLV2461QD	TLV2460QPW TLV2461QPW	— —	— —	— —
	1500 μV	TLV2460AQD TLV2461AQD	TLV2460AQPW TLV2461AQPW	— —	— —	— —
-55°C to 125°C	2000 μV	— —	— —	TLV2460MJG TLV2461MJG	TLV2460MU TLV2461MU	TLV2460MFK TLV2461MFK
	1500 μV	— —	— —	TLV2460AMJG TLV2461AMJG	TLV2460AMU TLV2461AMU	TLV2460AMFK TLV2461AMFK

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2460QDR).

### TLV2462C//AI and TLV2463C//AI AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IOmax</sub> AT 25°C	PACKAGED DEVICES						
		SMALL OUTLINE† (D)	MSOP (DGK)	SYMBOL	MSOP† (DGS)	SYMBOL	PLASTIC DIP (N)	PLASTIC DIP (P)
0°C to 70°C	2000 μV	TLV2462CD TLV2463CD	TLV2462CDGK —	xxTIAAI	— TLV2463CDGS	— xxTIAAK	— TLV2463CN	TLV2462CP —
-40°C to 125°C	2000 μV	TLV2462ID TLV2463ID	TLV2462IDGK —	xxTIAAJ	— TLV2463IDGS	— xxTIAAL	— TLV2463IN	TLV2462IP —
	1500 μV	TLV2462AID TLV2463AID	— —	— —	— —	— —	— TLV2463AIN	TLV2462AIP —

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2462CDR).

‡ Chip forms are tested at T<sub>A</sub> = 25°C only.

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## TLV2462M/AM/Q/AQ and TLV2463M/AM/Q/AQ AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IO</sub> max AT 25°C	PACKAGED DEVICES					
		SMALL OUTLINE† (D)	SMALL OUTLINE† (PW)	CERAMIC DIP (JG)	CERAMIC DIP (J)	CERAMIC FLATPACK (U)	CHIP CAR- RIER (FK)
-40°C to 125°C	2000 μV	TLV2462QD TLV2463QD	TLV2462QPW TLV2463QPW	— —	— —	— —	— —
	1500 μV	TLV2462AQD TLV2463AQD	TLV2462AQPW TLV2463AQPW	— —	— —	— —	— —
-55°C to 125°C	2000 μV	— —	— —	TLV2462MJG —	— TLV2463MJ	TLV2462MU	TLV2462MFK TLV2463MFK
	1500 μV	— —	— —	TLV2462AMJG —	— TLV2463AMJ	TLV2462AMU	TLV2462AMFK TLV2463AMFK

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2462QDR).

## TLV2464C//AI and TLV2465C//AI AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IO</sub> max AT 25°C	PACKAGED DEVICES		
		SMALL OUTLINE (D)	PLASTIC DIP (N)	TSSOP (PW)
0°C to 70°C	2000 μV	TLV2464CD TLV2465CD	TLV2464CN TLV2465CN	TLV2464CPW TLV2465CPW
-40°C to 125°C	2000 μV	TLV2464ID TLV2465ID	TLV2464IN TLV2465IN	TLV2464IPW TLV2465IPW
	1500 μV	TLV2464AID TLV2465AID	TLV2464AIN TLV2465AIN	TLV2464AIPW TLV2465AIPW

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2464CDR).

‡ Chip forms are tested at T<sub>A</sub> = 25°C only.

## TLV2464M/AM/Q/AQ and TLV2465M/AM/Q/AQ AVAILABLE OPTIONS

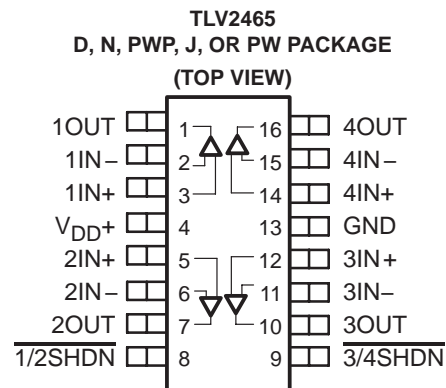
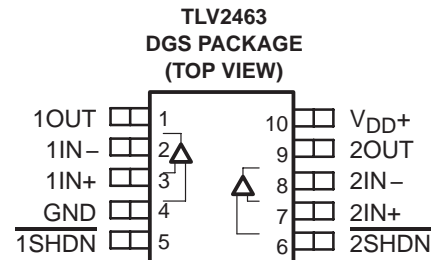
T <sub>A</sub>	V <sub>IO</sub> max AT 25°C	PACKAGED DEVICES			
		SMALL OUTLINE† (D)	SMALL OUTLINE† (PW)	CERAMIC DIP (J)	CHIP CARRIER (FK)
-40°C to 125°C	2000 μV	TLV2464QD TLV2465QD	TLV2464QPW TLV2465QPW	— —	— —
	1500 μV	TLV2464AQD TLV2465AQD	TLV2464AQPW TLV2465AQPW	— —	— —
-55°C to 125°C	2000 μV	— —	— —	TLV2464MJ TLV2465MJ	TLV2464MFK TLV2465MFK
	1500 μV	— —	— —	TLV2464AMJ TLV2465AMJ	TLV2464AMFK TLV2465AMFK

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2464QDR).

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## TLV246x PACKAGE PINOUTS(1)



NC – No internal connection  
(1) SOT-23 may or may not be indicated

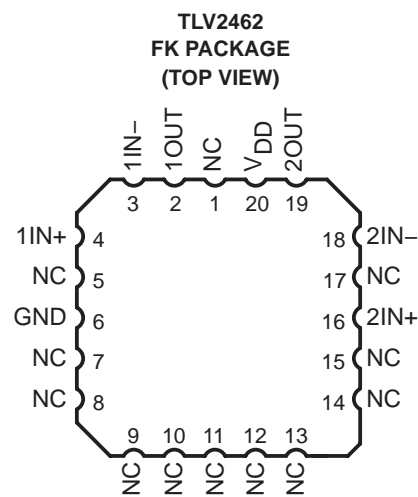
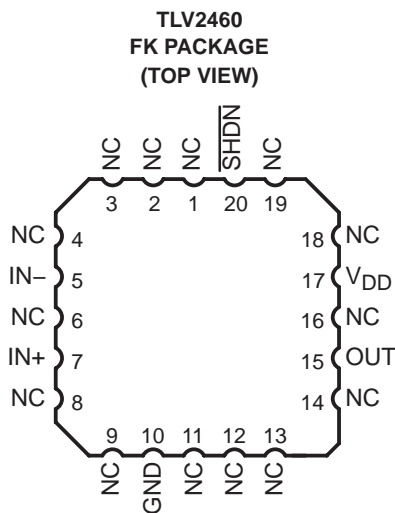
### TYPICAL PIN 1 INDICATORS



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## TLV246x PACKAGE PINOUTS (continued)(1)



NC – No internal connection  
(1) SOT-23 may or may not be indicated

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## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{DD}$ (see Note 1)	6 V
Differential input voltage, $V_{ID}$	– 0.2 V to $V_{DD} + 0.2$ V
Input current, $I_I$ (any input)	± 200 mA
Output current, $I_O$	± 175 mA
Total input current, $I_I$ (into $V_{DD+}$ )	175 mA
Total output current, $I_O$ (out of GND)	175 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, $T_A$ : C suffix	0°C to 70°C
I and Q suffix	–40°C to 125°C
M suffix	–55°C to 125°C
Maximum junction temperature, $T_J$	150°C
Storage temperature range, $T_{stg}$	–65°C to 150°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to GND.

DISSIPATION RATING TABLE FOR C and I SUFFIX

PACKAGE	$\theta_{JC}$ (°C/W)	$\theta_{JA}$ (°C/W)	$T_A \leq 25^\circ\text{C}$ POWER RATING	$T_A < 125^\circ\text{C}$ POWER RATING
D (8)	38.3	176	710 mW	142 mW
D (14)	26.9	122.6	1022 mW	204.4 mW
D (16)	25.7	114.7	1090 mW	218 mW
DBV (5)	55	324.1	385 mW	77.1 mW
DBV (6)	55	294.3	425 mW	84.9 mW
DGK	54.2	259.9	481 mW	96.2 mW
DGS	54.1	257.7	485 mW	97 mW
N (14, 16)	32	78	1600 mW	320.5 mW
P (8)	41	104	1200 mW	240.4 mW
PW (14)	29.3	173.6	720 mW	144 mW
PW (16)	28.7	161.4	774 mW	154.9 mW

NOTE: Thermal resistances are not production tested and are for informational purposes only.

DISSIPATION RATING TABLE FOR Q and M SUFFIX

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}^\ddagger$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
FK	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW
U	675 mW	5.4 mW/°C	432 mW	350 mW	135 mW

‡ This is the inverse of the traditional junction-to-ambient thermal resistance ( $R\theta_{JA}$ ). Thermal resistances are not production tested and are for informational purposes only.

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### recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, $V_{DD}$	Single supply	2.7	6	V
	Split supply	$\pm 1.35$	$\pm 3$	
Common-mode input voltage range, $V_{ICR}$		0	$V_{DD}$	V
Operating free-air temperature, $T_A$	C-suffix	0	70	°C
	I-suffix and Q-suffix	-40	125	
	M-suffix	-55	125	
Shutdown on/off voltage level <sup>‡</sup>	$V_{IH}$	2		V
	$V_{IL}$		0.7	

<sup>‡</sup> Relative to voltage on the GND terminal of the device.

### electrical characteristics at specified free-air temperature, $V_{DD} = 3\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$T_A$ <sup>†</sup>	MIN	TYP	MAX	UNIT
$V_{IO}$ Input offset voltage	$V_{DD} = 3\text{ V}$ , $V_{IC} = 1.5\text{ V}$ , $V_O = 1.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		500	2000	$\mu\text{V}$
		Full range			2200	
		25°C	TLV246xA	500	1500	
		Full range			1700	
$\alpha_{V_{IO}}$ Temperature coefficient of input offset voltage				2		$\mu\text{V}/^\circ\text{C}$
$I_{IO}$ Input offset current	$V_{DD} = 3\text{ V}$ , $V_{IC} = 1.5\text{ V}$ , $V_O = 1.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		2.8	7	nA
		Full range	TLV246xC		20	
$I_{IB}$ Input bias current	$V_{DD} = 3\text{ V}$ , $V_{IC} = 1.5\text{ V}$ , $V_O = 1.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		4.4	14	nA
		Full range	TLV246xC		25	
$V_{OH}$ High-level output voltage	$I_{OH} = -2.5\text{ mA}$	25°C		2.9		V
		Full range		2.8		
$V_{OH}$ High-level output voltage	$I_{OH} = -10\text{ mA}$	25°C		2.7		V
		Full range		2.5		
$V_{OL}$ Low-level output voltage	$V_{IC} = 1.5\text{ V}$ , $I_{OL} = 2.5\text{ mA}$	25°C		0.1		V
		Full range			0.2	
	$V_{IC} = 1.5\text{ V}$ , $I_{OL} = 10\text{ mA}$	25°C		0.3		
		Full range			0.5	
$I_{OS}$ Short-circuit output current	Sourcing	25°C		50		mA
		Full range		20		
	Sinking	25°C		40		
		Full range		20		
$I_O$ Output current	Measured 1 V from rail	25°C		$\pm 40$		mA
$A_{VD}$ Large-signal differential voltage amplification	$R_L = 10\text{ k}\Omega$ , $V_O(PP) = 1\text{ V}$	25°C		90	105	dB
		Full range		89		
$r_{i(d)}$ Differential input resistance		25°C		$10^9$		$\Omega$

<sup>†</sup> Full range is 0°C to 70°C for the C suffix, -40°C to 125°C for the I and Q suffixes, and -55°C to 125°C for the M suffix.

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electrical characteristics at specified free-air temperature,  $V_{DD} = 3\text{ V}$  (unless otherwise noted)  
(continued)

PARAMETER		TEST CONDITIONS		$T_A^\dagger$	MIN	TYP	MAX	UNIT
$C_i(c)$	Common-mode input capacitance	$f = 10\text{ kHz}$		$25^\circ\text{C}$		7		pF
$Z_o$	Closed-loop output impedance	$f = 100\text{ kHz}$ ,	$A_V = 10$	$25^\circ\text{C}$		33		$\Omega$
CMRR	Common-mode rejection ratio	$V_{ICR} = 0\text{ to }3\text{ V}$ , $R_S = 50\ \Omega$		$25^\circ\text{C}$	66	80		dB
				TLV246xC	Full range	64		
				TLV246xI/Q/M	Full range	60		
$k_{SVR}$	Supply voltage rejection ratio ( $\Delta V_{DD} / \Delta V_{IO}$ )	$V_{DD} = 2.7\text{ V to }6\text{ V}$ , No load	$V_{IC} = V_{DD}/2$ ,	$25^\circ\text{C}$	80	85		dB
				Full range	75			
				$25^\circ\text{C}$	85	95		
				Full range	80			
$I_{DD}$	Supply current (per channels)	$V_O = 1.5\text{ V}$ ,	No load	$25^\circ\text{C}$		0.5	0.575	mA
				Full range			0.9	
$I_{DD}(SHDN)$	Supply current in shutdown (TLV2460, TLV2463, TLV2465)	$\overline{SHDN} < 0.7\text{ V}$ , Per channel in shutdown		$25^\circ\text{C}$		0.3		$\mu\text{A}$
				Full range			2.5	

$\dagger$  Full range is  $0^\circ\text{C}$  to  $70^\circ\text{C}$  for the C suffix,  $-40^\circ\text{C}$  to  $125^\circ\text{C}$  for the I and Q suffixes, and  $-55^\circ\text{C}$  to  $125^\circ\text{C}$  for the M suffix.

operating characteristics at specified free-air temperature,  $V_{DD} = 3\text{ V}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A^\dagger$	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	$V_{O(PP)} = 0.8\text{ V}$ , $R_L = 10\text{ k}\Omega$	$C_L = 160\text{ pF}$ ,	$25^\circ\text{C}$	0.9	1.6		$\text{V}/\mu\text{s}$
				Full range	0.8			
$V_n$	Equivalent input noise voltage	$f = 100\text{ Hz}$		$25^\circ\text{C}$		16		$\text{nV}/\sqrt{\text{Hz}}$
				$25^\circ\text{C}$		11		
$I_n$	Equivalent input noise current	$f = 1\text{ kHz}$		$25^\circ\text{C}$		0.13		$\text{pA}/\sqrt{\text{Hz}}$
THD + N	Total harmonic distortion plus noise	$V_{O(PP)} = 2\text{ V}$ , $R_L = 10\text{ k}\Omega$ , $f = 1\text{ kHz}$		$25^\circ\text{C}$	$A_V = 1$	0.006%		
					$A_V = 10$	0.02%		
					$A_V = 100$	0.08%		
$t_{(on)}$	Amplifier turnon time	$A_V = 1$ , $R_L = 10\text{ k}\Omega$		$25^\circ\text{C}$	Both channels	7.6		$\mu\text{s}$
					Channel 1 only, Channel 2 on	7.65		
$t_{(off)}$	Amplifier turnoff time	$A_V = 1$ , $R_L = 10\text{ k}\Omega$		$25^\circ\text{C}$	Both channels	333		ns
					Channel 1 only, Channel 2 on	328		
					Channel 2 only, Channel 1 on	329		
Gain-bandwidth product		$f = 10\text{ kHz}$ , $C_L = 160\text{ pF}$	$R_L = 10\text{ k}\Omega$ ,	$25^\circ\text{C}$		5.2		MHz
$t_s$	Settling time	$V_{(STEP)PP} = 2\text{ V}$ , $A_V = -1$ , $C_L = 10\text{ pF}$ , $R_L = 10\text{ k}\Omega$		$25^\circ\text{C}$	0.1%	1.47		$\mu\text{s}$
					0.01%	1.78		
		$V_{(STEP)PP} = 2\text{ V}$ , $A_V = -1$ , $C_L = 56\text{ pF}$ , $R_L = 10\text{ k}\Omega$			0.1%	1.77		
					0.01%	1.98		
$\phi_m$	Phase margin at unity gain	$R_L = 10\text{ k}\Omega$ ,	$C_L = 160\text{ pF}$	$25^\circ\text{C}$		44°		
Gain margin				$25^\circ\text{C}$		7		dB

$\dagger$  Full range is  $0^\circ\text{C}$  to  $70^\circ\text{C}$  for the C suffix,  $-40^\circ\text{C}$  to  $125^\circ\text{C}$  for the I and Q suffixes, and  $-55^\circ\text{C}$  to  $125^\circ\text{C}$  for the M suffix.



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electrical characteristics at specified free-air temperature,  $V_{DD} = 5\text{ V}$  (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$T_A$ †	MIN	TYP	MAX	UNIT
$V_{IO}$ Input offset voltage	$V_{DD} = 5\text{ V}$ , $V_{IC} = 2.5\text{ V}$ , $V_O = 2.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		500	2000	$\mu\text{V}$
		Full range			2200	
		25°C		500	1500	
		Full range			1700	
$\alpha_{VIO}$ Temperature coefficient of input offset voltage		25°C		2		$\mu\text{V}/^\circ\text{C}$
$I_{IO}$ Input offset current	$V_{DD} = 5\text{ V}$ , $V_{IC} = 2.5\text{ V}$ , $V_O = 2.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		0.3	7	nA
		TLV246xC	Full range		15	
		TLV246xI/Q/M	Full range		60	
$I_{IB}$ Input bias current	$V_{DD} = 5\text{ V}$ , $V_{IC} = 2.5\text{ V}$ , $V_O = 2.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		1.3	14	nA
		TLV246xC	Full range		30	
		TLV246xI/Q/M	Full range		60	
$V_{OH}$ High-level output voltage	$I_{OH} = -2.5\text{ mA}$	25°C		4.9		V
		Full range	4.8			
	$I_{OH} = -10\text{ mA}$	25°C		4.8		
		Full range	4.7			
$V_{OL}$ Low-level output voltage	$V_{IC} = 2.5\text{ V}$ , $I_{OL} = 2.5\text{ mA}$	25°C		0.1		V
		Full range			0.2	
	$V_{IC} = 2.5\text{ V}$ , $I_{OL} = 10\text{ mA}$	25°C		0.2		
		Full range			0.3	
$I_{OS}$ Short-circuit output current	Sourcing	25°C		145		mA
		Full range	60			
	Sinking	25°C		100		
		Full range	60			
$I_O$ Output current	Measured at 1 V from rail	25°C		$\pm 80$		mA
$A_{VD}$ Large-signal differential voltage amplification	$V_{IC} = 2.5\text{ V}$ , $V_O = 1\text{ V to }4\text{ V}$	$R_L = 10\text{ k}\Omega$	25°C	92	109	dB
			Full range	90		
$r_{i(d)}$ Differential input resistance		25°C		$10^9$		$\Omega$
$c_{i(c)}$ Common-mode input capacitance	$f = 10\text{ kHz}$	25°C		7		pF
$z_o$ Closed-loop output impedance	$f = 100\text{ kHz}$ , $A_V = 10$	25°C		29		$\Omega$
CMRR Common-mode rejection ratio	$V_{ICR} = 0\text{ V to }5\text{ V}$ , $R_S = 50\ \Omega$	25°C	71	85		dB
		TLV246xC	Full range	69		
		TLV246xI/Q/M	Full range	60		
$k_{SVR}$ Supply voltage rejection ratio ( $\Delta V_{DD} / \Delta V_{IO}$ )	$V_{DD} = 2.7\text{ V to }6\text{ V}$ , No load	$V_{IC} = V_{DD}/2$	25°C	80	85	dB
			Full range	75		
	$V_{DD} = 3\text{ V to }5\text{ V}$ , No load	$V_{IC} = V_{DD}/2$	25°C	85	95	dB
			Full range	80		
$I_{DD}$ Supply current (per channel)	$V_O = 2.5\text{ V}$ , No load,	25°C		0.55	0.65	mA
		Full range			1	
$I_{DD(SHDN)}$ Supply current in shutdown (TLV2460, TLV2463, TLV2465)	$\overline{\text{SHDN}} < 0.7\text{ V}$ , Per channels in shutdown	25°C		1		$\mu\text{A}$
		Full range			3	

† Full range is 0°C to 70°C for the C suffix, -40°C to 125°C for the I and Q suffixes, and -55°C to 125°C for the M suffix.

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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operating characteristics at specified free-air temperature,  $V_{DD} = 5\text{ V}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A$ †	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	$V_{O(PP)} = 2\text{ V}$ , $R_L = 10\text{ k}\Omega$	$C_L = 160\text{ pF}$	25°C	0.9	1.6		$\text{V}/\mu\text{s}$
				Full range	0.8			
$V_n$	Equivalent input noise voltage			25°C	14			$\text{nV}/\sqrt{\text{Hz}}$
				25°C	11			
$I_n$	Equivalent input noise current	$f = 100\text{ Hz}$		25°C	0.13			$\text{pA}/\sqrt{\text{Hz}}$
THD + N	Total harmonic distortion plus noise	$V_{O(PP)} = 4\text{ V}$ , $R_L = 10\text{ k}\Omega$ , $f = 10\text{ kHz}$		25°C	$A_V = 1$		0.004%	
					$A_V = 10$		0.01%	
					$A_V = 100$		0.04%	
$t_{(on)}$	Amplifier turnon time	$A_V = 1$ , $R_L = 10\text{ k}\Omega$		25°C	Both channels		7.6	$\mu\text{s}$
					Channel 1 only, Channel 2 on		7.65	
					Channel 2 only, Channel 1 on		7.25	
$t_{(off)}$	Amplifier turnoff time	$A_V = 1$ , $R_L = 10\text{ k}\Omega$		25°C	Both channels		333	ns
					Channel 1 only, Channel 2 on		328	
					Channel 2 only, Channel 1 on		329	
Gain-bandwidth product		$f = 10\text{ kHz}$ , $C_L = 160\text{ pF}$	$R_L = 10\text{ k}\Omega$	25°C	6.4			MHz
$t_s$	Settling time	$V_{(STEP)PP} = 2\text{ V}$ , $A_V = -1$ , $C_L = 10\text{ pF}$ , $R_L = 10\text{ k}\Omega$		25°C	0.1%		1.53	$\mu\text{s}$
					0.01%		1.83	
		$V_{(STEP)PP} = 2\text{ V}$ , $A_V = -1$ , $C_L = 56\text{ pF}$ , $R_L = 10\text{ k}\Omega$			0.1%		3.13	
					0.01%		3.33	
$\phi_m$	Phase margin at unity gain	$R_L = 10\text{ k}\Omega$ , $C_L = 160\text{ pF}$		25°C	45°			
	Gain margin			25°C	7			dB

† Full range is 0°C to 70°C for the C suffix, -40°C to 125°C for the I and Q suffixes, and -55°C to 125°C for the M suffix.

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## TYPICAL CHARACTERISTICS

### Table of Graphs

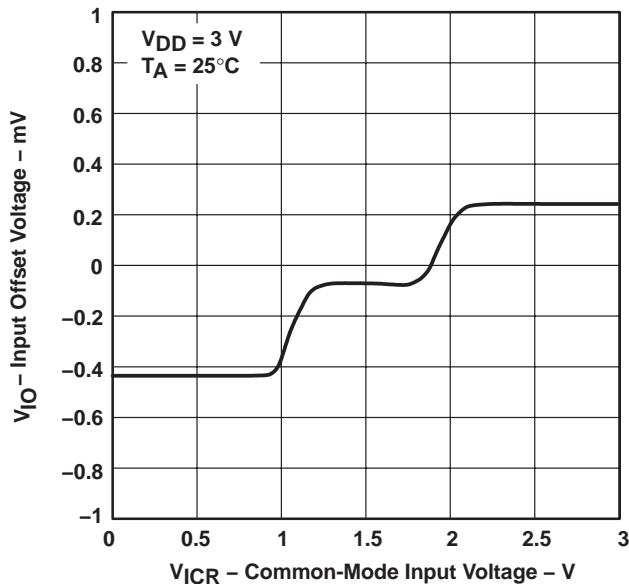
			FIGURE
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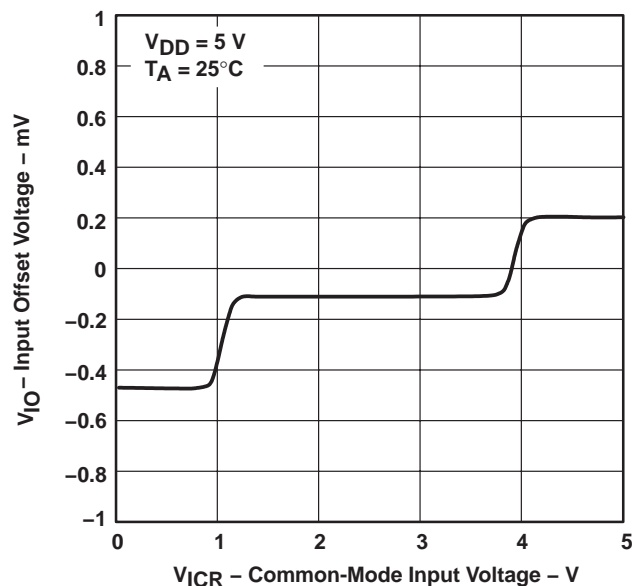
**TYPICAL CHARACTERISTICS**

**INPUT OFFSET VOLTAGE**  
**vs**  
**COMMON-MODE INPUT VOLTAGE**



**Figure 1**

**INPUT OFFSET VOLTAGE**  
**vs**  
**COMMON-MODE INPUT VOLTAGE**



**Figure 2**

**INPUT BIAS AND INPUT OFFSET CURRENT**  
**vs**  
**FREE-AIR TEMPERATURE**



**Figure 3**

**INPUT BIAS AND INPUT OFFSET CURRENT**  
**vs**  
**FREE-AIR TEMPERATURE**



**Figure 4**

TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
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TYPICAL CHARACTERISTICS



Figure 5

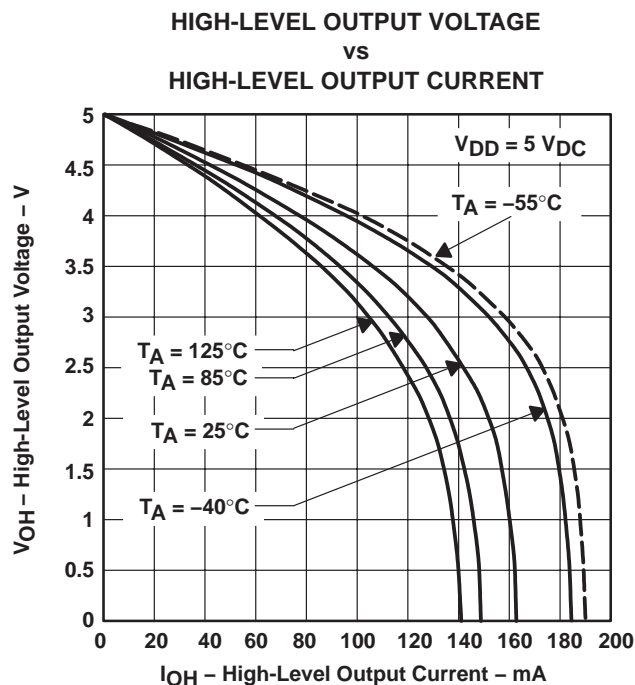


Figure 6



Figure 7

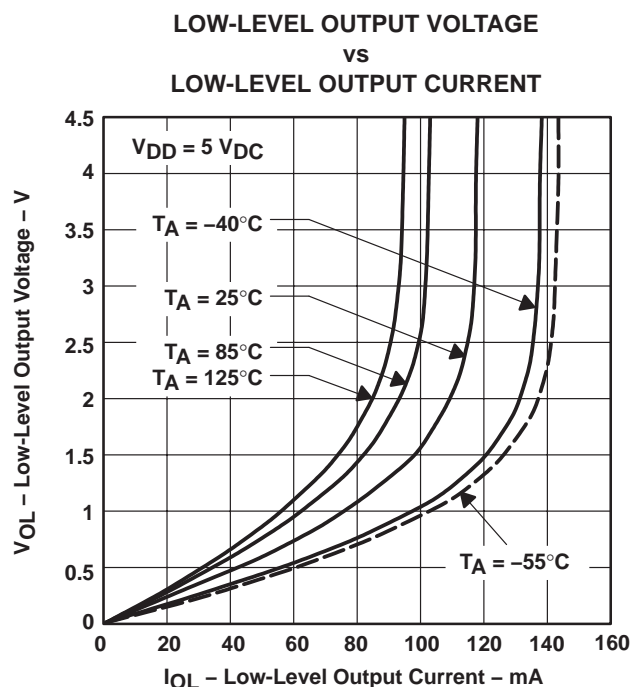
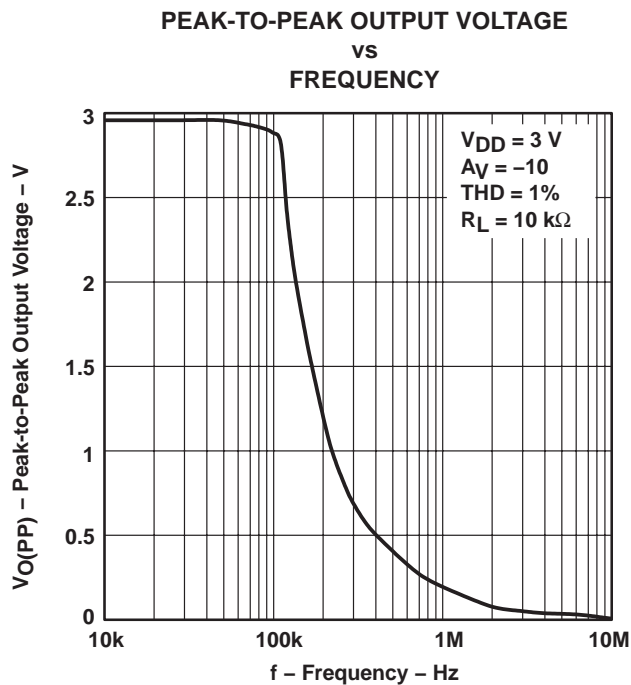


Figure 8

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
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**TYPICAL CHARACTERISTICS**



# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## TYPICAL CHARACTERISTICS

### OPEN-LOOP GAIN AND PHASE vs FREQUENCY



Figure 12

### DIFFERENTIAL VOLTAGE AMPLIFICATION vs LOAD RESISTANCE



Figure 13

### CAPACITIVE LOAD vs LOAD RESISTANCE

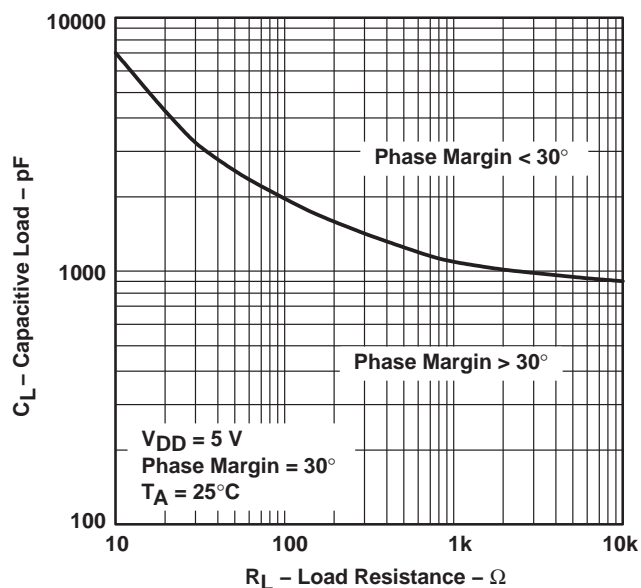


Figure 14

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
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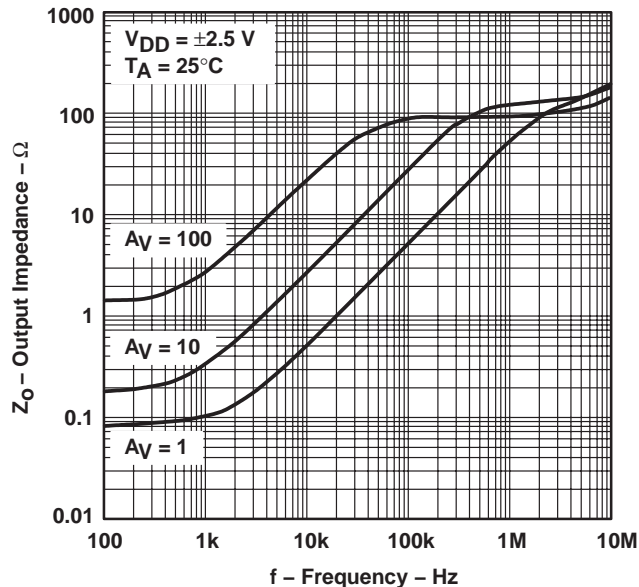
**TYPICAL CHARACTERISTICS**

**OUTPUT IMPEDANCE**  
**vs**  
**FREQUENCY**



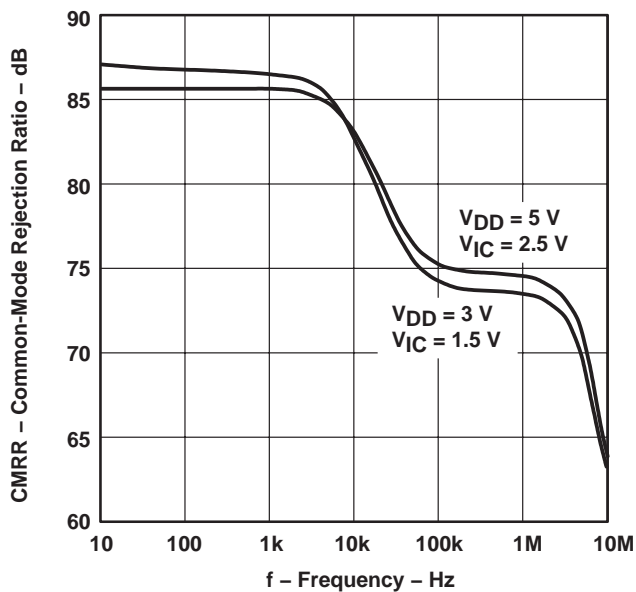
**Figure 15**

**OUTPUT IMPEDANCE**  
**vs**  
**FREQUENCY**



**Figure 16**

**COMMON-MODE REJECTION RATIO**  
**vs**  
**FREQUENCY**



**Figure 17**



# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## TYPICAL CHARACTERISTICS



Figure 18

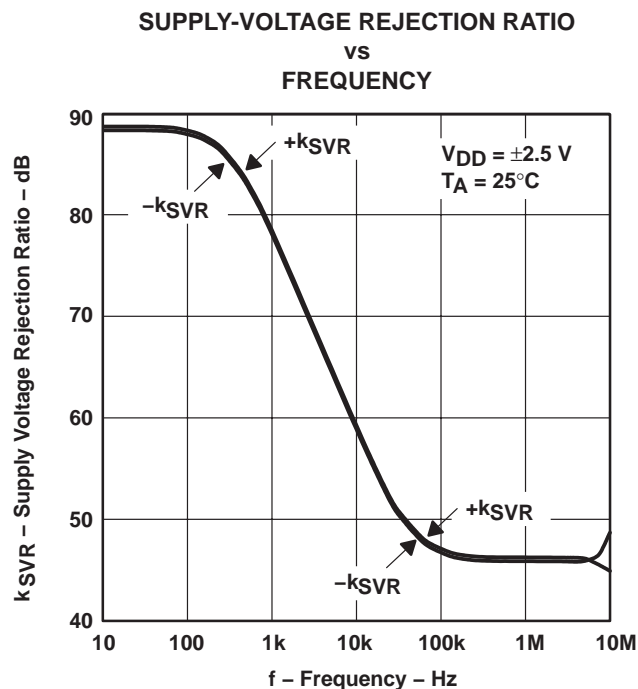


Figure 19

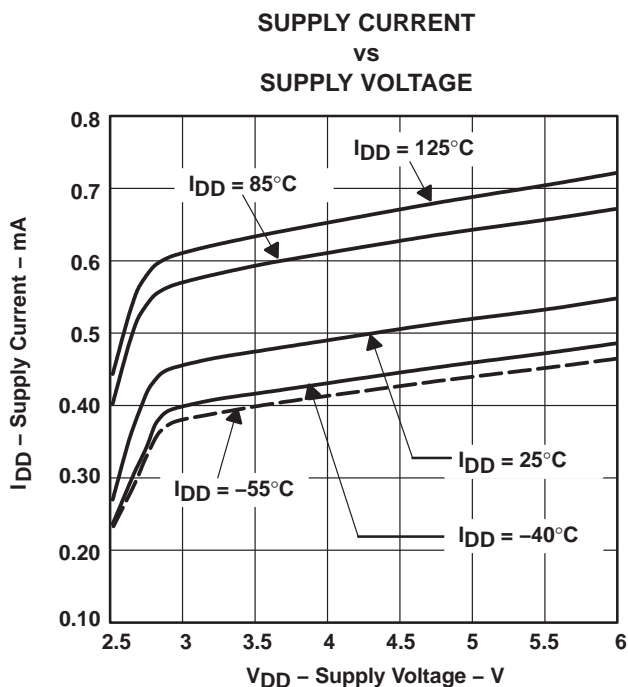


Figure 20

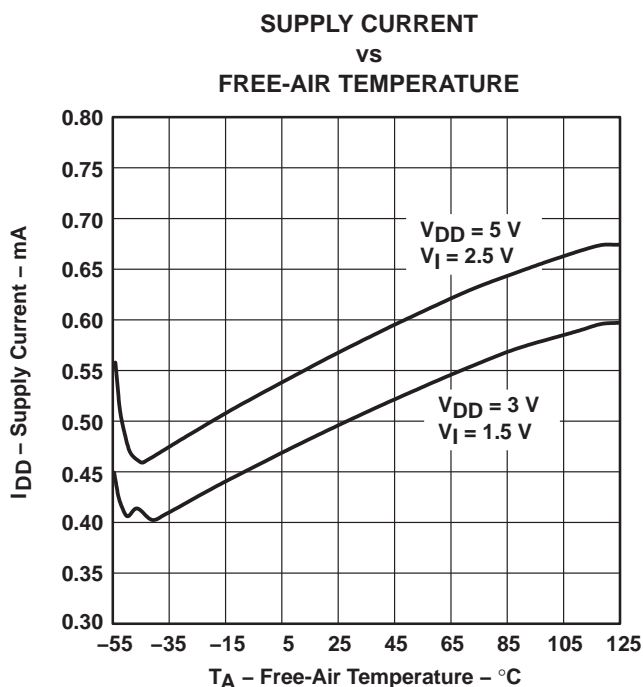


Figure 21

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
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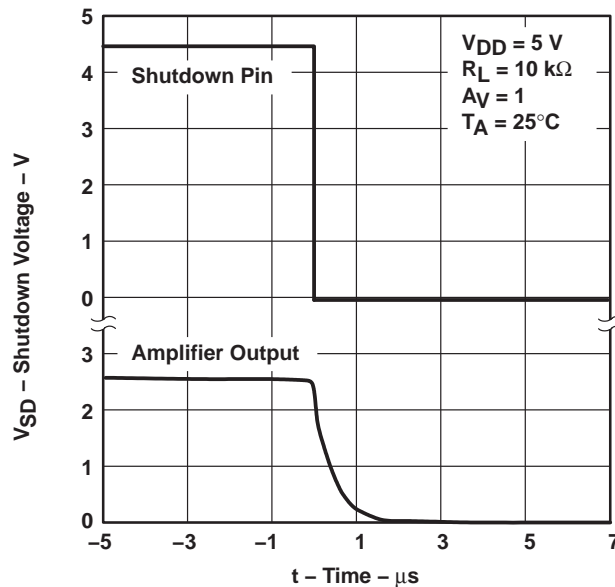
**TYPICAL CHARACTERISTICS**

**AMPLIFIER WITH A SHUTDOWN PULSE  
 TURNON CHARACTERISTICS**



**Figure 22**

**AMPLIFIER WITH A SHUTDOWN PULSE  
 TURNOFF CHARACTERISTICS**



**Figure 23**

**SUPPLY CURRENT WITH A SHUTDOWN PULSE  
 TURNON CHARACTERISTICS**



**Figure 24**

TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
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TYPICAL CHARACTERISTICS

TURN-OFF SUPPLY CURRENT  
 WITH A SHUTDOWN PULSE



Figure 25

SHUTDOWN SUPPLY CURRENT  
 vs  
 FREE-AIR TEMPERATURE



Figure 26

SLEW RATE  
 vs  
 SUPPLY VOLTAGE



Figure 27

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
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**TYPICAL CHARACTERISTICS**

**EQUIVALENT INPUT NOISE VOLTAGE  
 vs  
 FREQUENCY**



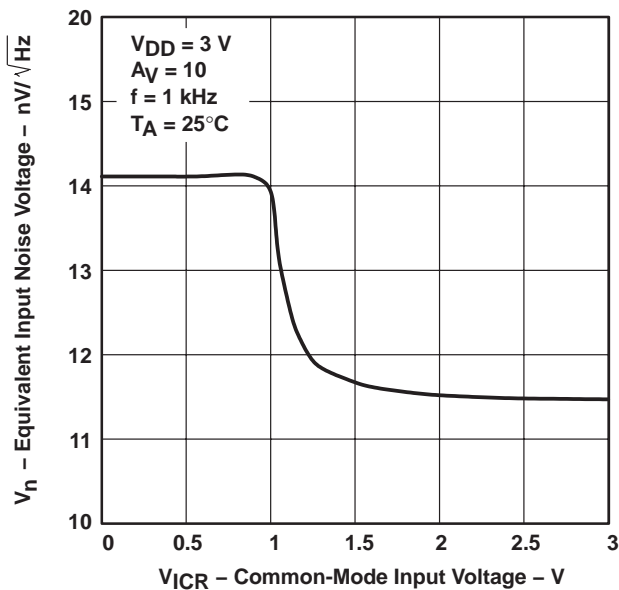
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**EQUIVALENT INPUT NOISE VOLTAGE  
 vs  
 FREQUENCY**



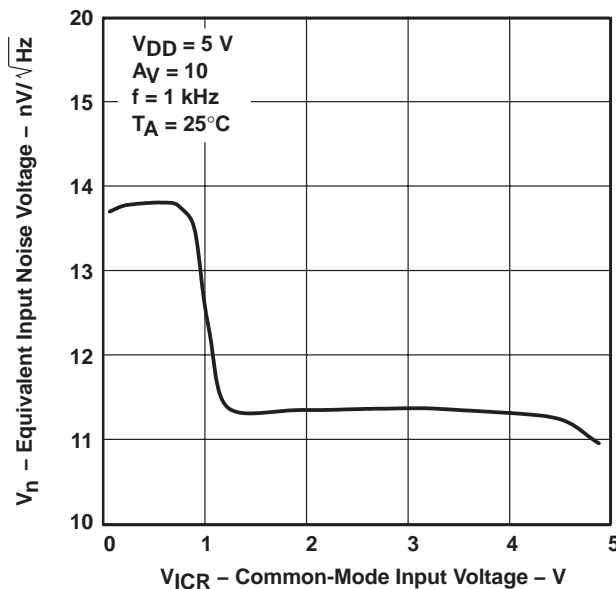
**Figure 29**

**EQUIVALENT INPUT NOISE VOLTAGE  
 vs  
 COMMON-MODE INPUT VOLTAGE**



**Figure 30**

**EQUIVALENT INPUT NOISE VOLTAGE  
 vs  
 COMMON-MODE INPUT VOLTAGE**



**Figure 31**

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## TYPICAL CHARACTERISTICS



Figure 32



Figure 33

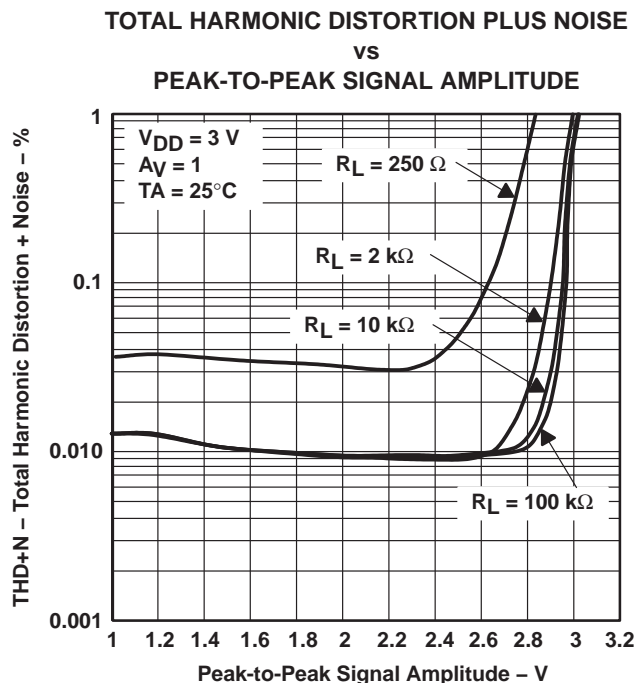


Figure 34

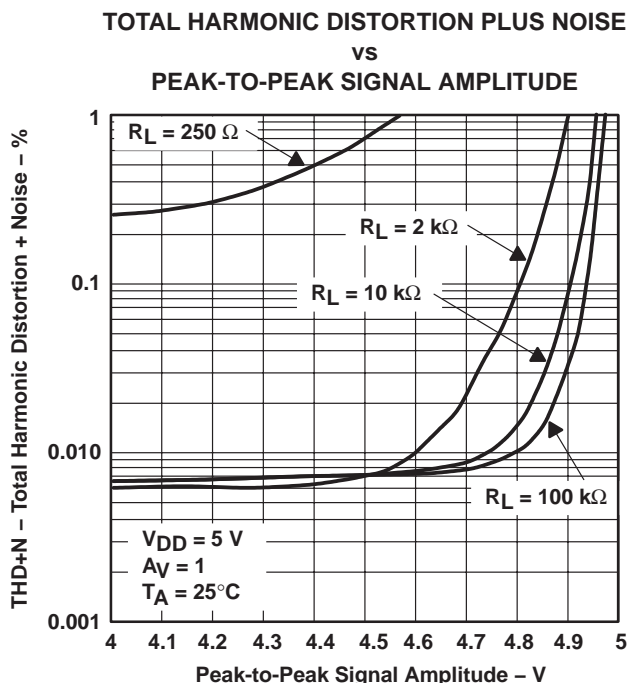


Figure 35

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## TYPICAL CHARACTERISTICS



Figure 36



Figure 37

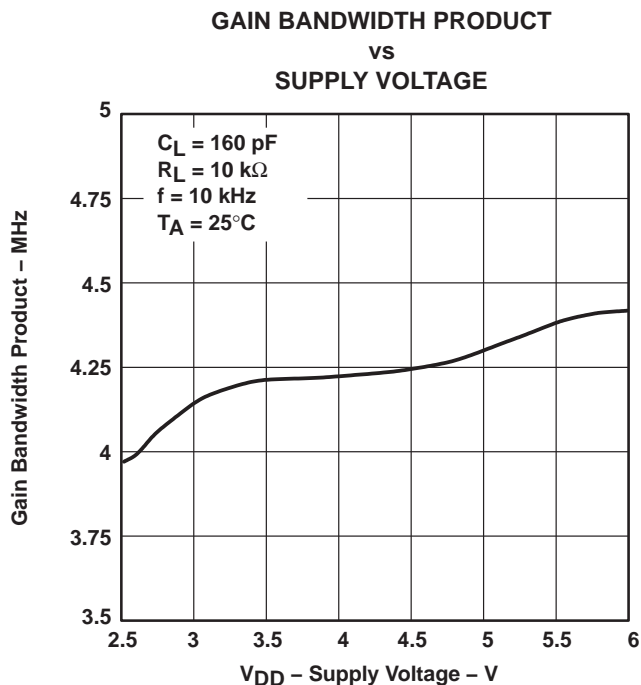


Figure 38

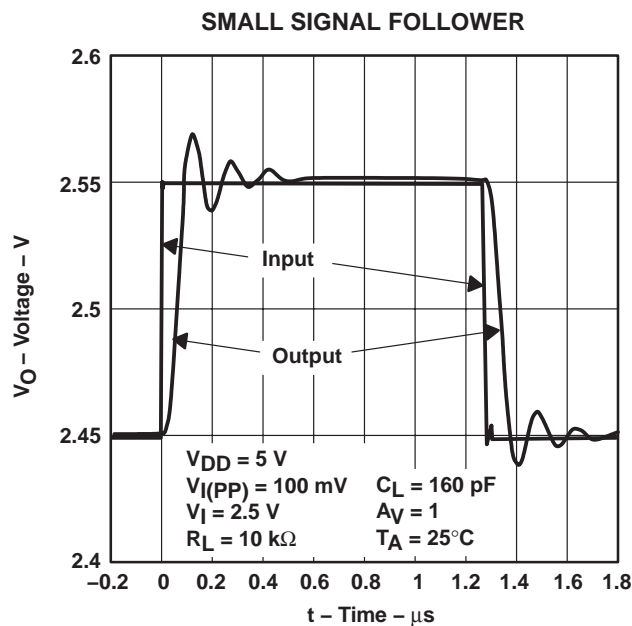
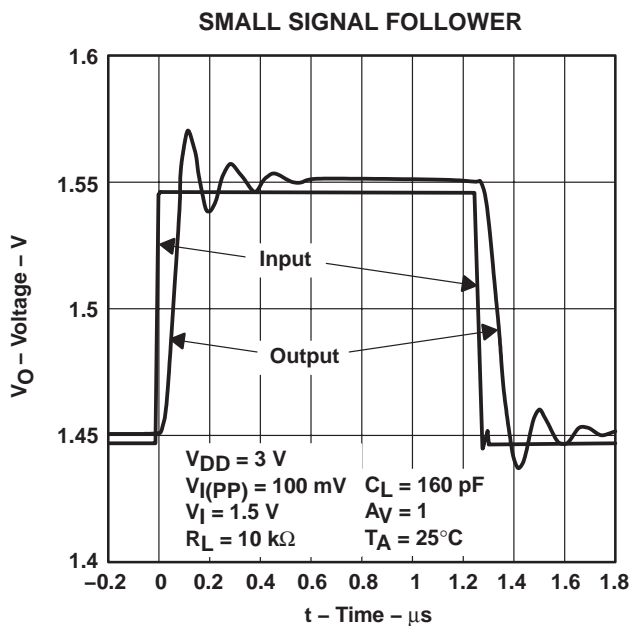
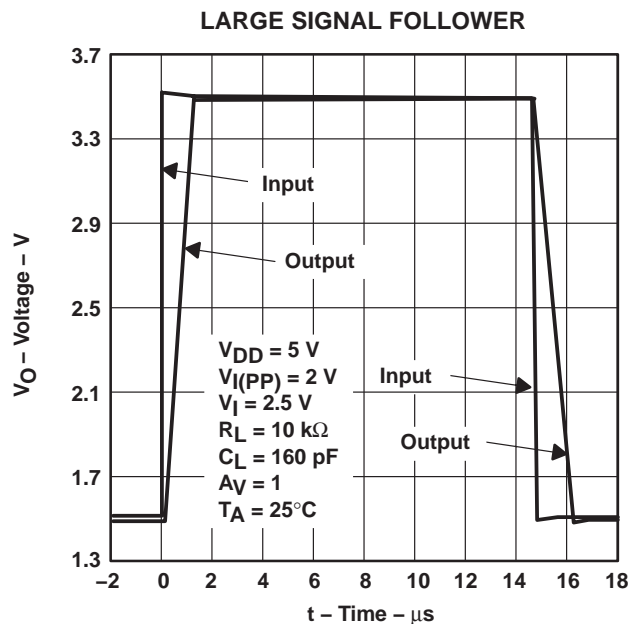
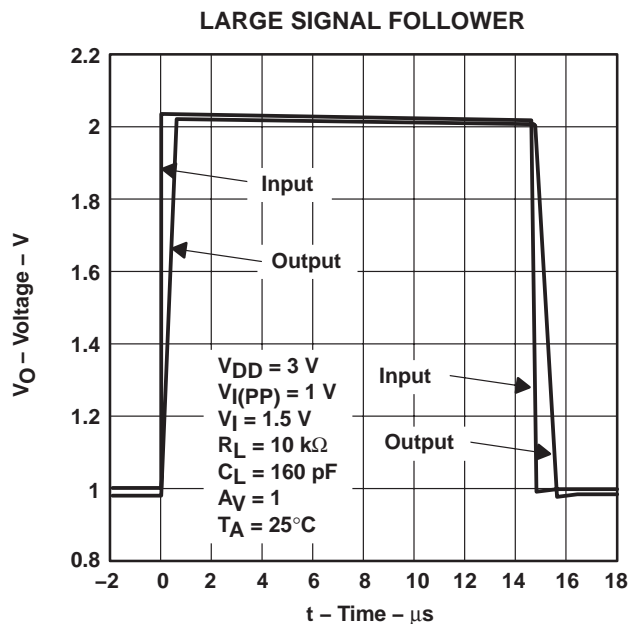


Figure 39

TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
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TYPICAL CHARACTERISTICS



**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
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**TYPICAL CHARACTERISTICS**



**Figure 44**



**Figure 45**



**Figure 46**



**Figure 47**



# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## PARAMETER MEASUREMENT INFORMATION

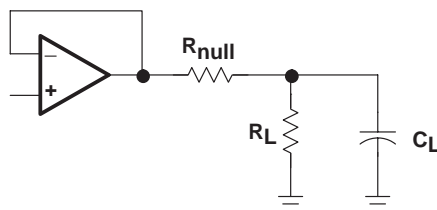


Figure 48

## APPLICATION INFORMATION

### driving a capacitive load

When the amplifier is configured in this manner, capacitive loading directly on the output will decrease the device's phase margin leading to high frequency ringing or oscillations. Therefore, for capacitive loads of greater than 10 pF, it is recommended that a resistor be placed in series ( $R_{NULL}$ ) with the output of the amplifier, as shown in Figure 49. A minimum value of 20  $\Omega$  should work well for most applications.



Figure 49. Driving a Capacitive Load

### offset voltage

The output offset voltage, ( $V_{OO}$ ) is the sum of the input offset voltage ( $V_{IO}$ ) and both input bias currents ( $I_{IB}$ ) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage:



Figure 50. Output Offset Voltage Model

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## APPLICATION INFORMATION

### general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 51).



Figure 51. Single-Pole Low-Pass Filter

If even more attenuation is needed, a multiple pole filter is required. The Sallen-Key filter can be used for this task. For best results, the amplifier should have a bandwidth that is 8 to 10 times the filter frequency bandwidth. Failure to do this can result in phase shift of the amplifier.



Figure 52. 2-Pole Low-Pass Sallen-Key Filter

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## APPLICATION INFORMATION

### shutdown function

Three members of the TLV246x family (TLV2460/3/5) have a shutdown terminal for conserving battery life in portable applications. When the shutdown terminal is tied low, the supply current is reduced to 0.3  $\mu\text{A}/\text{channel}$ , the amplifier is disabled, and the outputs are placed in a high impedance mode. To enable the amplifier, the shutdown terminal can either be left floating or pulled high. When the shutdown terminal is left floating, care should be taken to ensure that parasitic leakage current at the shutdown terminal does not inadvertently place the operational amplifier into shutdown. The shutdown terminal threshold is always referenced to  $V_{\text{DD}}/2$ . Therefore, when operating the device with split supply voltages (e.g.  $\pm 2.5\text{ V}$ ), the shutdown terminal needs to be pulled to  $V_{\text{DD-}}$  (not GND) to disable the operational amplifier.

The amplifier's output with a shutdown pulse is shown in Figures 22, 23, 24, and 25. The amplifier is powered with a single 5-V supply and configured as a noninverting configuration with a gain of 5. The amplifier turnon and turnoff times are measured from the 50% point of the shutdown pulse to the 50% point of the output waveform. The times for the single, dual, and quad are listed in the data tables.

### circuit layout considerations

To achieve the levels of high performance of the TLV246x, follow proper printed-circuit board design techniques. A general set of guidelines is given in the following.

- Ground planes – It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- Proper power supply decoupling – Use a 6.8- $\mu\text{F}$  tantalum capacitor in parallel with a 0.1- $\mu\text{F}$  ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1- $\mu\text{F}$  ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1- $\mu\text{F}$  capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- Sockets – Sockets can be used but are not recommended. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- Short trace runs/compact part placements – Optimum high performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This will help to minimize stray capacitance at the input of the amplifier.
- Surface-mount passive components – Using surface-mount passive components is recommended for high performance amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## APPLICATION INFORMATION

### general power dissipation considerations

For a given  $\theta_{JA}$ , the maximum power dissipation is shown in Figure 53 and is calculated by the following formula:

$$P_D = \left( \frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

Where:

$P_D$  = Maximum power dissipation of THS246x IC (watts)

$T_{MAX}$  = Absolute maximum junction temperature (150°C)

$T_A$  = Free-ambient air temperature (°C)

$\theta_{JA}$  =  $\theta_{JC} + \theta_{CA}$

$\theta_{JC}$  = Thermal coefficient from junction to case

$\theta_{CA}$  = Thermal coefficient from case to ambient air (°C/W)



NOTE A: Results are with no air flow and using JEDEC Standard Low-K test PCB.

**Figure 53. Maximum Power Dissipation vs Free-Air Temperature**

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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## APPLICATION INFORMATION

### macromodel information

Macromodel information provided was derived using Microsim *Parts*™ Release 8, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 2) and subcircuit in Figure 54 are generated using the TLV246x typical electrical and operating characteristics at  $T_A = 25^\circ\text{C}$ . Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

NOTE 2: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers", *IEEE Journal of Solid-State Circuits*, SC-9, 353 (1974).



Figure 54. Boyle Macromodels and Subcircuit

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# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

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### macromodel information (continued)

```

.subckt TLV_246Y 1 2 3 4 5 6
  c1      11      12      2.4603E-12
  c2      72      7       10.000E-12
  css     10      99      443.21E-15
  dc      70      53      dy
  de      54      70      dy
  dlp     90      91      dx
  dln     92      90      dx
  dp      4       3       dx
  egnd    99      0       poly(2) (3,0) (4,0) 0 .5 .5
  fb      7       99      poly(5) vb vc ve vlp vln 0
21.600E6 -1E3 1E3 22E6 -22E6
  ga      72      0       11 12 345.26E-6
  gcm     0       72      10 99 15.422E-9
  iss     74      4       dc 18.850E-6
  hlim    90      0       vlim 1K
  j1      11      2       10 jx1
  j2      12      1       10 jx2
  r2      72      9       100.00E3
  rd1     3       11      2.8964E3
  rd2     3       12      2.8964E3
  ro1     8       70      5.6000
  ro2     7       99      6.2000
  rp      3       71      8.9127
  rss     10      99      10.610E6
  rs1     6       4       1G
  rs2     6       4       1G
  rs3     6       4       1G
  rs4     6       4       1G
  s1      71      4       6 4 s1x
  s2      70      5       6 4 s1x
  s3      10      74      6 4 s1x
  s4      74      4       6 4 s2x
  vb      9       0       dc 0
  vc      3       53      dc .7836
  ve      54      4       dc .7436
  vlim    7       8       dc 0
  vlp     91      0       dc 117
  vln     0       92      dc 117
.model dx D(Is=800.00E-18)
.model dy D(Is=800.00E-18 Rs=1m Cjo=10p)
.model jx1 NJF(Is=1.0000E-12 Beta=6.3239E-3 Vto=-1)
.model jx2 NJF(Is=1.0000E-12 Beta=6.3239E-3 Vto=-1)
.model s1x VSWITCH(Roff=1E8 Ron=1.0 Voff=2.5 Von=0.0)
.model s2x VSWITCH(Roff=1E8 Ron=1.0 Voff=0 Von=2.5)
.ends

```

Figure 54. Boyle Macromodels and Subcircuit (Continued)

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">5962-0051201QHA</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051201QHA TLV2460M
<a href="#">5962-0051203QHA</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051203QHA TLV2461M
<a href="#">5962-0051205QHA</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051205QHA TLV2462M
<a href="#">5962-0051206Q2A</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 0051206Q2A TLV2462A MFKB
<a href="#">5962-0051206QHA</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051206QHA TLV2462AM
<a href="#">5962-0051206QPA</a>	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051206QPA TLV2462AM
<a href="#">TLV2460AIDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2460AI
TLV2460AIDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2460AI
<a href="#">TLV2460AIP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2460AI
TLV2460AIP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2460AI
<a href="#">TLV2460CD</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2460C
TLV2460CD.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2460C
<a href="#">TLV2460CDBVR</a>	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAOC
TLV2460CDBVR.A	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAOC
<a href="#">TLV2460CDBVT</a>	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAOC
TLV2460CDBVT.A	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAOC
TLV2460CDBVTG4	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	-	Call TI	Call TI	0 to 70	
<a href="#">TLV2460CDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2460C
TLV2460CDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2460C
<a href="#">TLV2460CP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2460C
TLV2460CP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2460C
<a href="#">TLV2460ID</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2460I
TLV2460ID.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2460I

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLV2460IDBVR</a>	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAOI
TLV2460IDBVR.A	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAOI
<a href="#">TLV2460IDBVT</a>	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAOI
TLV2460IDBVT.A	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAOI
<a href="#">TLV2460IDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2460I
TLV2460IDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2460I
<a href="#">TLV2460IP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2460I
TLV2460IP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2460I
<a href="#">TLV2460MUB</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051201QHA TLV2460M
TLV2460MUB.A	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051201QHA TLV2460M
<a href="#">TLV2461AID</a>	Obsolete	Production	SOIC (D)   8	-	-	Call TI	Call TI	-40 to 125	2461AI
<a href="#">TLV2461AIDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2461AI
TLV2461AIDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2461AI
<a href="#">TLV2461AIP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2461AI
TLV2461AIP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2461AI
<a href="#">TLV2461CD</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2461C
TLV2461CD.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2461C
<a href="#">TLV2461CDBVR</a>	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAPC
TLV2461CDBVR.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAPC
<a href="#">TLV2461CDBVT</a>	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAPC
TLV2461CDBVT.A	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	VAPC
<a href="#">TLV2461CDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2461C
TLV2461CDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2461C
<a href="#">TLV2461CP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2461C
TLV2461CP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2461C
<a href="#">TLV2461ID</a>	Obsolete	Production	SOIC (D)   8	-	-	Call TI	Call TI	-40 to 125	2461I
<a href="#">TLV2461IDBVR</a>	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAPI
TLV2461IDBVR.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAPI
<a href="#">TLV2461IDBVT</a>	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAPI



Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLV2461IDBVT.A	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VAPI
<a href="#">TLV2461IDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2461I
TLV2461IDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2461I
<a href="#">TLV2461IP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2461I
TLV2461IP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2461I
<a href="#">TLV2461MUB</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051203QHA TLV2461M
TLV2461MUB.A	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051203QHA TLV2461M
<a href="#">TLV2462AID</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AI
TLV2462AID.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AI
TLV2462AID.B	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AI
<a href="#">TLV2462AIDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AI
TLV2462AIDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AI
TLV2462AIDR.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462AI
<a href="#">TLV2462AIP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2462AI
TLV2462AIP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2462AI
<a href="#">TLV2462AMFKB</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 0051206Q2A TLV2462A MFKB
TLV2462AMFKB.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 0051206Q2A TLV2462A MFKB
<a href="#">TLV2462AMJG</a>	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TLV2462AMJG
TLV2462AMJG.A	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TLV2462AMJG
<a href="#">TLV2462AMJGB</a>	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051206QPA TLV2462AM
TLV2462AMJGB.A	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051206QPA TLV2462AM
<a href="#">TLV2462AMUB</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051206QHA TLV2462AM

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLV2462AMUB.A	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051206QHA TLV2462AM
<a href="#">TLV2462AQD</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
TLV2462AQD.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
TLV2462AQD.B	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
<a href="#">TLV2462AQDG4</a>	Obsolete	Production	SOIC (D)   8	-	-	Call TI	Call TI	-	V2462A
<a href="#">TLV2462AQDRG4</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	V2462A
TLV2462AQDRG4.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
TLV2462AQDRG4.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
<a href="#">TLV2462AQPWR</a>	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
TLV2462AQPWR.A	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
TLV2462AQPWR.B	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462A
<a href="#">TLV2462CD</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2462C
TLV2462CD.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2462C
TLV2462CD.B	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2462C
TLV2462CDG4	Active	Production	SOIC (D)   8	75   TUBE	-	Call TI	Call TI	0 to 70	
<a href="#">TLV2462CDGK</a>	Active	Production	VSSOP (DGK)   8	80   TUBE	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	0 to 70	AAI
TLV2462CDGK.A	Active	Production	VSSOP (DGK)   8	80   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AAI
<a href="#">TLV2462CDGKR</a>	Active	Production	VSSOP (DGK)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AAI
TLV2462CDGKR.B	Active	Production	VSSOP (DGK)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AAI
TLV2462CDGKRG4	Active	Production	VSSOP (DGK)   8	2500   LARGE T&R	-	Call TI	Call TI	0 to 70	
<a href="#">TLV2462CDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2462C
TLV2462CDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2462C
TLV2462CDR.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2462C
TLV2462CDRG4	Active	Production	SOIC (D)   8	2500   LARGE T&R	-	Call TI	Call TI	0 to 70	
<a href="#">TLV2462CP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2462CP
TLV2462CP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2462CP
TLV2462CP.B	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2462CP
TLV2462CPE4	Active	Production	PDIP (P)   8	50   TUBE	-	Call TI	Call TI	0 to 70	
<a href="#">TLV2462ID</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462I
TLV2462ID.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462I

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLV2462ID.B	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462I
TLV2462IDG4	Active	Production	SOIC (D)   8	75   TUBE	-	Call TI	Call TI	-40 to 125	
<a href="#">TLV2462IDGK</a>	Active	Production	VSSOP (DGK)   8	80   TUBE	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	AAJ
TLV2462IDGK.A	Active	Production	VSSOP (DGK)   8	80   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AAJ
TLV2462IDGKG4	Active	Production	VSSOP (DGK)   8	80   TUBE	-	Call TI	Call TI	-40 to 125	
<a href="#">TLV2462IDGKR</a>	Active	Production	VSSOP (DGK)   8	2500   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	AAJ
TLV2462IDGKR.B	Active	Production	VSSOP (DGK)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AAJ
<a href="#">TLV2462IDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462I
TLV2462IDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462I
TLV2462IDR.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2462I
<a href="#">TLV2462IP</a>	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2462IP
TLV2462IP.A	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2462IP
TLV2462IP.B	Active	Production	PDIP (P)   8	50   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2462IP
<a href="#">TLV2462MUB</a>	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051205QHA TLV2462M
TLV2462MUB.A	Active	Production	CFP (U)   10	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	0051205QHA TLV2462M
<a href="#">TLV2462QPWR</a>	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462Q
TLV2462QPWR.A	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462Q
TLV2462QPWR.B	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462Q
<a href="#">TLV2462QPWRG4</a>	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	V2462Q
TLV2462QPWRG4.A	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462Q
TLV2462QPWRG4.B	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	V2462Q
<a href="#">TLV2463AIDR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2463AI
TLV2463AIDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2463AI
TLV2463AIDR.B	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2463AI
TLV2463AMFKB	Obsolete	Production	LCCC (FK)   20	-	-	Call TI	Call TI	-	5962- 0051208Q2A TLV2463 AMFKB
<a href="#">TLV2463AMJ</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TLV2463AMJ
TLV2463AMJ.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TLV2463AMJ

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLV2463CDGS</a>	Active	Production	VSSOP (DGS)   10	80   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AAK
TLV2463CDGS.A	Active	Production	VSSOP (DGS)   10	80   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AAK
<a href="#">TLV2463CDGSR</a>	Active	Production	VSSOP (DGS)   10	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AAK
TLV2463CDGSR.B	Active	Production	VSSOP (DGS)   10	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AAK
<a href="#">TLV2463CDR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2463C
TLV2463CDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2463C
TLV2463CDR.B	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2463C
<a href="#">TLV2463CN</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2463CN
TLV2463CN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2463CN
<a href="#">TLV2463ID</a>	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2463I
TLV2463ID.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2463I
TLV2463ID.B	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2463I
<a href="#">TLV2463IDGS</a>	Active	Production	VSSOP (DGS)   10	80   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AAL
TLV2463IDGS.B	Active	Production	VSSOP (DGS)   10	80   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AAL
<a href="#">TLV2463IDGSR</a>	Active	Production	VSSOP (DGS)   10	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AAL
TLV2463IDGSR.B	Active	Production	VSSOP (DGS)   10	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AAL
<a href="#">TLV2463IN</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2463IN
TLV2463IN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2463IN
<a href="#">TLV2464AID</a>	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2464AI
TLV2464AID.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2464AI
TLV2464AIDG4	Active	Production	SOIC (D)   14	50   TUBE	-	Call TI	Call TI	-40 to 125	
<a href="#">TLV2464AIDR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2464AI
TLV2464AIDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2464AI
TLV2464AIDRG4	Active	Production	SOIC (D)   14	2500   LARGE T&R	-	Call TI	Call TI	-40 to 125	
<a href="#">TLV2464AIN</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2464AIN
TLV2464AIN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2464AIN
<a href="#">TLV2464AIPW</a>	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464A
TLV2464AIPW.A	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464A
<a href="#">TLV2464AIPWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	TY2464A
TLV2464AIPWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464A
<a href="#">TLV2464AIPWRG4</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464A

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLV2464CD</a>	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2464C
TLV2464CD.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2464C
<a href="#">TLV2464CDR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2464C
TLV2464CDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2464C
<a href="#">TLV2464CN</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2464CN
TLV2464CN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TLV2464CN
TLV2464CNE4	Active	Production	PDIP (N)   14	25   TUBE	-	Call TI	Call TI	0 to 70	
<a href="#">TLV2464CPW</a>	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV2464
TLV2464CPW.A	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV2464
<a href="#">TLV2464CPWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	TV2464
TLV2464CPWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV2464
<a href="#">TLV2464ID</a>	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2464I
TLV2464ID.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2464I
TLV2464ID.B	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2464I
TLV2464IDG4	Active	Production	SOIC (D)   14	50   TUBE	-	Call TI	Call TI	-40 to 125	
<a href="#">TLV2464IDR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2464I
TLV2464IDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2464I
<a href="#">TLV2464IN</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2464IN
TLV2464IN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2464IN
<a href="#">TLV2464IPW</a>	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464
TLV2464IPW.A	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464
<a href="#">TLV2464IPWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464
TLV2464IPWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TY2464
TLV2464IPWRG4	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	-	Call TI	Call TI	-40 to 125	
<a href="#">TLV2465CD</a>	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	0 to 70	
<a href="#">TLV2465CDR</a>	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2465C
TLV2465CDR.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV2465C
<a href="#">TLV2465CPWR</a>	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2465C
TLV2465CPWR.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	2465C
<a href="#">TLV2465ID</a>	Active	Production	SOIC (D)   16	40   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2465I
TLV2465ID.A	Active	Production	SOIC (D)   16	40   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2465I

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLV2465IDR</a>	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2465I
TLV2465IDR.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV2465I
<a href="#">TLV2465IN</a>	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2465IN
TLV2465IN.A	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	TLV2465IN
<a href="#">TLV2465IPW</a>	Active	Production	TSSOP (PW)   16	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2465I
TLV2465IPW.A	Active	Production	TSSOP (PW)   16	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2465I
TLV2465IPW.B	Active	Production	TSSOP (PW)   16	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2465I
<a href="#">TLV2465IPWR</a>	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2465I
TLV2465IPWR.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2465I

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF TLV2460, TLV2460A, TLV2460M, TLV2461, TLV2461A, TLV2461M, TLV2462, TLV2462A, TLV2462AM, TLV2462M, TLV2463A, TLV2463AM, TLV2464A :**

- Catalog : [TLV2460](#), [TLV2461](#), [TLV2462A](#), [TLV2462](#), [TLV2463A](#)
  
- Automotive : [TLV2460A-Q1](#), [TLV2461A-Q1](#), [TLV2462-Q1](#), [TLV2462A-Q1](#), [TLV2462A-Q1](#), [TLV2462-Q1](#), [TLV2463A-Q1](#), [TLV2463A-Q1](#), [TLV2464A-Q1](#)
  
- Enhanced Product : [TLV2462A-EP](#), [TLV2462A-EP](#), [TLV2464A-EP](#)
  
- Military : [TLV2460M](#), [TLV2461M](#), [TLV2462M](#), [TLV2462AM](#), [TLV2463AM](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
  
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
  
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
  
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV2460AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2460CDBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV2460CDBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV2460CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2460IDBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV2460IDBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV2460IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2461AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2461CDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TLV2461CDBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TLV2461CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2461IDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TLV2461IDBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
TLV2461IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2462AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2462AQPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV2462CDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TLV2462CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2462IDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TLV2462IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV2462QPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLV2462QPWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLV2463AIDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV2463CDGSR	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TLV2463CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV2463IDGSR	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TLV2464AIDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV2464AIPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV2464AIPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV2464CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV2464CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV2464IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV2464IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV2465CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TLV2465CPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV2465IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV2460AIDR	SOIC	D	8	2500	340.5	338.1	20.6
TLV2460CDBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TLV2460CDBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
TLV2460CDR	SOIC	D	8	2500	353.0	353.0	32.0
TLV2460IDBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TLV2460IDBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
TLV2460IDR	SOIC	D	8	2500	340.5	338.1	20.6
TLV2461AIDR	SOIC	D	8	2500	353.0	353.0	32.0
TLV2461CDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV2461CDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV2461CDR	SOIC	D	8	2500	353.0	353.0	32.0
TLV2461IDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TLV2461IDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TLV2461IDR	SOIC	D	8	2500	353.0	353.0	32.0
TLV2462AIDR	SOIC	D	8	2500	353.0	353.0	32.0
TLV2462AQPWR	TSSOP	PW	8	2000	353.0	353.0	32.0
TLV2462CDGKR	VSSOP	DGK	8	2500	358.0	335.0	35.0
TLV2462CDR	SOIC	D	8	2500	353.0	353.0	32.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV2462IDGKR	VSSOP	DGK	8	2500	358.0	335.0	35.0
TLV2462IDR	SOIC	D	8	2500	353.0	353.0	32.0
TLV2462QPWR	TSSOP	PW	8	2000	353.0	353.0	32.0
TLV2462QPWRG4	TSSOP	PW	8	2000	353.0	353.0	32.0
TLV2463AIDR	SOIC	D	14	2500	350.0	350.0	43.0
TLV2463CDGSR	VSSOP	DGS	10	2500	358.0	335.0	35.0
TLV2463CDR	SOIC	D	14	2500	350.0	350.0	43.0
TLV2463IDGSR	VSSOP	DGS	10	2500	358.0	335.0	35.0
TLV2464AIDR	SOIC	D	14	2500	333.2	345.9	28.6
TLV2464AIPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
TLV2464AIPWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
TLV2464CDR	SOIC	D	14	2500	353.0	353.0	32.0
TLV2464CPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
TLV2464IDR	SOIC	D	14	2500	353.0	353.0	32.0
TLV2464IPWR	TSSOP	PW	14	2000	353.0	353.0	32.0
TLV2465CDR	SOIC	D	16	2500	350.0	350.0	43.0
TLV2465CPWR	TSSOP	PW	16	2000	353.0	353.0	32.0
TLV2465IPWR	TSSOP	PW	16	2000	353.0	353.0	32.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-0051201QHA	U	CFP	10	25	506.98	26.16	6220	NA
5962-0051203QHA	U	CFP	10	25	506.98	26.16	6220	NA
5962-0051205QHA	U	CFP	10	25	506.98	26.16	6220	NA
5962-0051206Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-0051206QHA	U	CFP	10	25	506.98	26.16	6220	NA
TLV2460AIP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2460AIP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2460CD	D	SOIC	8	75	507	8	3940	4.32
TLV2460CD.A	D	SOIC	8	75	507	8	3940	4.32
TLV2460CP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2460CP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2460ID	D	SOIC	8	75	505.46	6.76	3810	4
TLV2460ID	D	SOIC	8	75	507	8	3940	4.32
TLV2460ID.A	D	SOIC	8	75	505.46	6.76	3810	4
TLV2460ID.A	D	SOIC	8	75	507	8	3940	4.32
TLV2460IP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2460IP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2460MUB	U	CFP	10	25	506.98	26.16	6220	NA
TLV2460MUB.A	U	CFP	10	25	506.98	26.16	6220	NA
TLV2461AIP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2461AIP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2461CD	D	SOIC	8	75	507	8	3940	4.32
TLV2461CD.A	D	SOIC	8	75	507	8	3940	4.32
TLV2461CP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2461CP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2461IP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2461IP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2461MUB	U	CFP	10	25	506.98	26.16	6220	NA
TLV2461MUB.A	U	CFP	10	25	506.98	26.16	6220	NA

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TLV2462AID	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462AID	D	SOIC	8	75	507	8	3940	4.32
TLV2462AID.A	D	SOIC	8	75	507	8	3940	4.32
TLV2462AID.A	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462AID.B	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462AID.B	D	SOIC	8	75	507	8	3940	4.32
TLV2462AIP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462AIP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462AMFKB	FK	LCCC	20	55	506.98	12.06	2030	NA
TLV2462AMFKB.A	FK	LCCC	20	55	506.98	12.06	2030	NA
TLV2462AMUB	U	CFP	10	25	506.98	26.16	6220	NA
TLV2462AMUB.A	U	CFP	10	25	506.98	26.16	6220	NA
TLV2462AQD	D	SOIC	8	75	507	8	3940	4.32
TLV2462AQD.A	D	SOIC	8	75	507	8	3940	4.32
TLV2462AQD.B	D	SOIC	8	75	507	8	3940	4.32
TLV2462CD	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462CD	D	SOIC	8	75	507	8	3940	4.32
TLV2462CD.A	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462CD.A	D	SOIC	8	75	507	8	3940	4.32
TLV2462CD.B	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462CD.B	D	SOIC	8	75	507	8	3940	4.32
TLV2462CDGK	DGK	VSSOP	8	80	330	6.55	500	2.88
TLV2462CDGK.A	DGK	VSSOP	8	80	330	6.55	500	2.88
TLV2462CP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462CP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462CP.B	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462ID	D	SOIC	8	75	507	8	3940	4.32
TLV2462ID	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462ID.A	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462ID.A	D	SOIC	8	75	507	8	3940	4.32
TLV2462ID.B	D	SOIC	8	75	505.46	6.76	3810	4
TLV2462ID.B	D	SOIC	8	75	507	8	3940	4.32
TLV2462IDGK	DGK	VSSOP	8	80	330	6.55	500	2.88
TLV2462IDGK.A	DGK	VSSOP	8	80	330	6.55	500	2.88
TLV2462IP	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462IP.A	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462IP.B	P	PDIP	8	50	506	13.97	11230	4.32
TLV2462MUB	U	CFP	10	25	506.98	26.16	6220	NA
TLV2462MUB.A	U	CFP	10	25	506.98	26.16	6220	NA
TLV2463CN	N	PDIP	14	25	506	13.97	11230	4.32
TLV2463CN.A	N	PDIP	14	25	506	13.97	11230	4.32
TLV2463ID	D	SOIC	14	50	505.46	6.76	3810	4
TLV2463ID.A	D	SOIC	14	50	505.46	6.76	3810	4

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TLV2463ID.B	D	SOIC	14	50	505.46	6.76	3810	4
TLV2463IN	N	PDIP	14	25	506	13.97	11230	4.32
TLV2463IN.A	N	PDIP	14	25	506	13.97	11230	4.32
TLV2464AID	D	SOIC	14	50	507	8	3940	4.32
TLV2464AID	D	SOIC	14	50	505.46	6.76	3810	4
TLV2464AID.A	D	SOIC	14	50	505.46	6.76	3810	4
TLV2464AID.A	D	SOIC	14	50	507	8	3940	4.32
TLV2464AIN	N	PDIP	14	25	506	13.97	11230	4.32
TLV2464AIN.A	N	PDIP	14	25	506	13.97	11230	4.32
TLV2464AIPW	PW	TSSOP	14	90	530	10.2	3600	3.5
TLV2464AIPW.A	PW	TSSOP	14	90	530	10.2	3600	3.5
TLV2464CD	D	SOIC	14	50	505.46	6.76	3810	4
TLV2464CD	D	SOIC	14	50	507	8	3940	4.32
TLV2464CD.A	D	SOIC	14	50	507	8	3940	4.32
TLV2464CD.A	D	SOIC	14	50	505.46	6.76	3810	4
TLV2464CN	N	PDIP	14	25	506	13.97	11230	4.32
TLV2464CN.A	N	PDIP	14	25	506	13.97	11230	4.32
TLV2464CPW	PW	TSSOP	14	90	530	10.2	3600	3.5
TLV2464CPW.A	PW	TSSOP	14	90	530	10.2	3600	3.5
TLV2464ID	D	SOIC	14	50	507	8	3940	4.32
TLV2464ID.A	D	SOIC	14	50	507	8	3940	4.32
TLV2464ID.B	D	SOIC	14	50	507	8	3940	4.32
TLV2464IN	N	PDIP	14	25	506	13.97	11230	4.32
TLV2464IN.A	N	PDIP	14	25	506	13.97	11230	4.32
TLV2464IPW	PW	TSSOP	14	90	530	10.2	3600	3.5
TLV2464IPW.A	PW	TSSOP	14	90	530	10.2	3600	3.5
TLV2465ID	D	SOIC	16	40	505.46	6.76	3810	4
TLV2465ID.A	D	SOIC	16	40	505.46	6.76	3810	4
TLV2465IN	N	PDIP	16	25	506	13.97	11230	4.32
TLV2465IN.A	N	PDIP	16	25	506	13.97	11230	4.32
TLV2465IPW	PW	TSSOP	16	90	530	10.2	3600	3.5
TLV2465IPW.A	PW	TSSOP	16	90	530	10.2	3600	3.5
TLV2465IPW.B	PW	TSSOP	16	90	530	10.2	3600	3.5



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

# DGS0010A



# PACKAGE OUTLINE

## VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4221984/A 05/2015

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187, variation BA.

# EXAMPLE BOARD LAYOUT

DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:10X



SOLDER MASK DETAILS  
NOT TO SCALE

4221984/A 05/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:10X

4221984/A 05/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017



4220204/B 12/2023

NOTES:

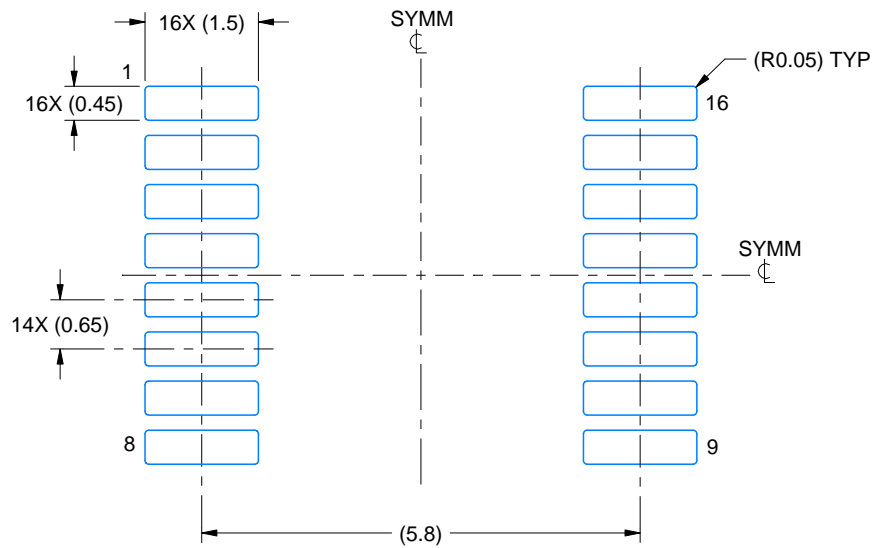
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



D0008A

# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed  $.006$  [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

# EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



4040082/E 04/2010

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001 variation BA.



N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 (C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 (D) The 20 pin end lead shoulder width is a vendor option, either half or full width.

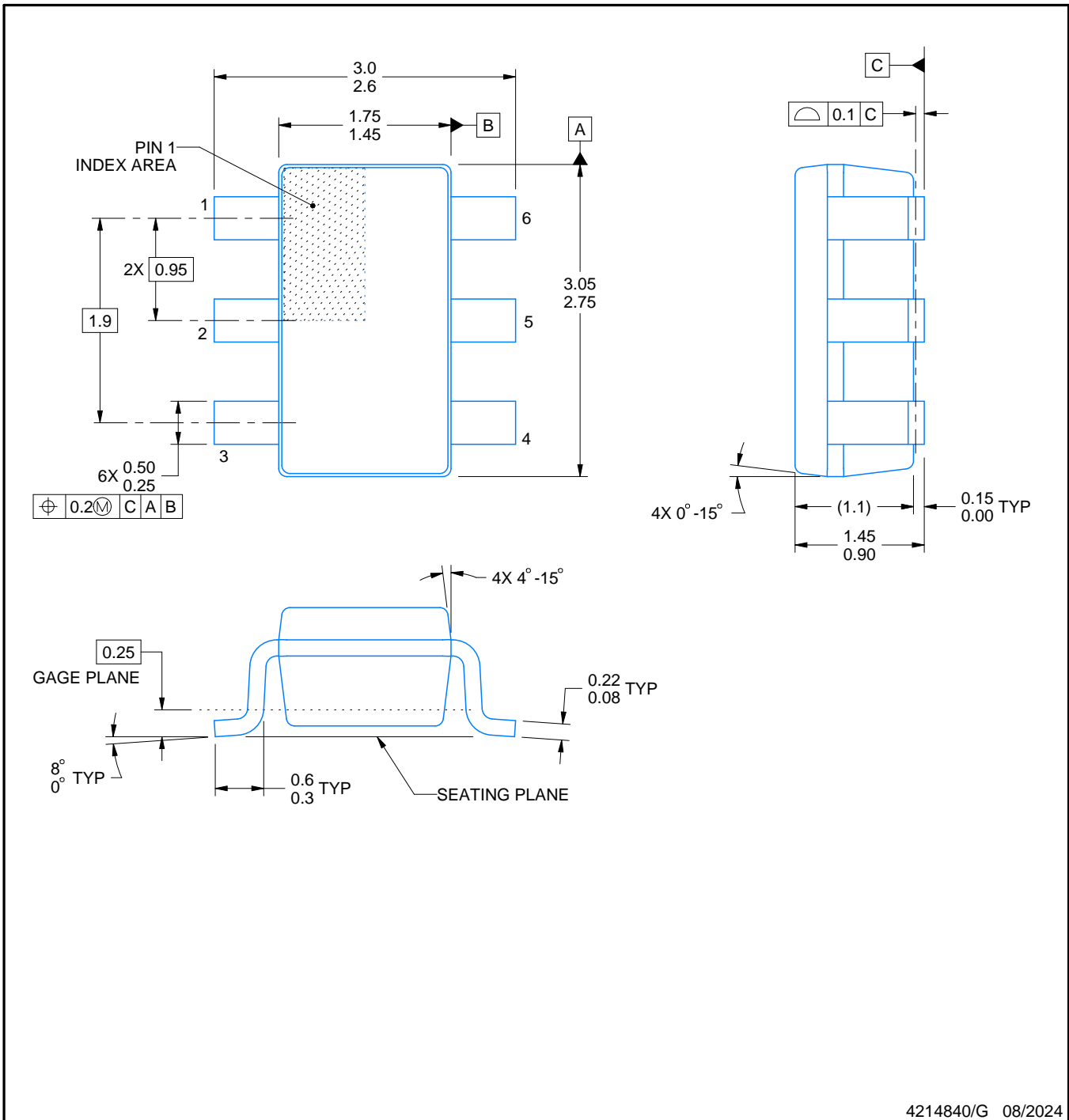
# DBV0006A



# PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



4214840/G 08/2024

**NOTES:**

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.
- Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Reference JEDEC MO-178.

# EXAMPLE BOARD LAYOUT

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214840/G 08/2024

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214840/G 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW0008A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4221848/A 02/2015

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.



# EXAMPLE BOARD LAYOUT

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:10X



SOLDER MASK DETAILS  
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# PACKAGE OUTLINE

## JG0008A

### CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE



4230036/A 09/2023

#### NOTES:

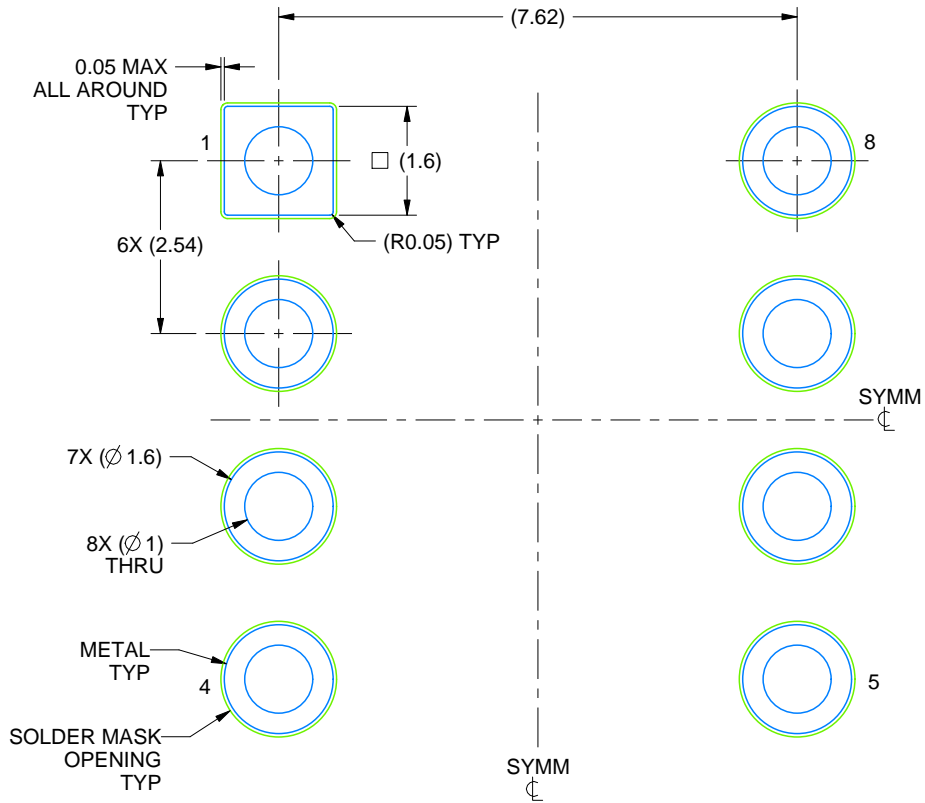
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package can be hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification.
5. Falls within MIL STD 1835 GDIP1-T8

# EXAMPLE BOARD LAYOUT

## JG0008A

## CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE



LAND PATTERN EXAMPLE  
NON SOLDER MASK DEFINED  
SCALE: 9X

4230036/A 09/2023

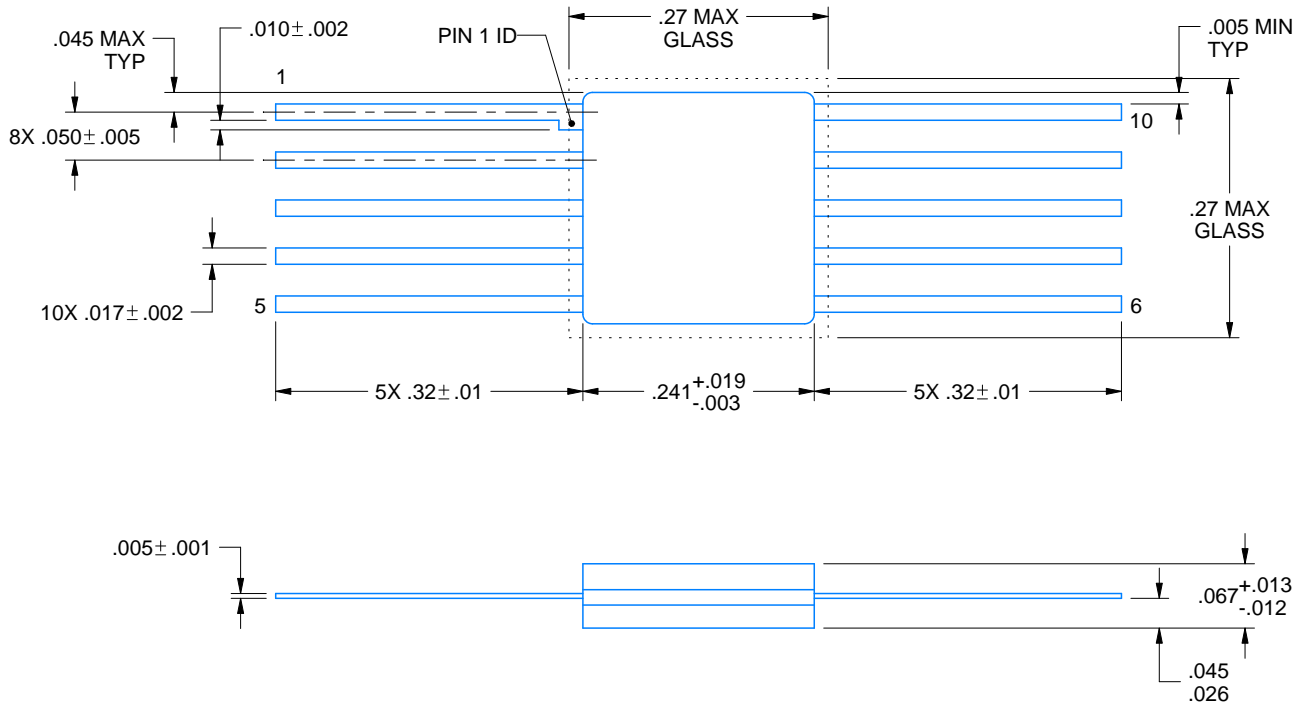
U0010A



# PACKAGE OUTLINE

CFP - 2.03 mm max height

CERAMIC FLATPACK



4225582/A 01/2020

NOTES:

1. All linear dimensions are in inches. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# DBV0005A



# PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

# EXAMPLE BOARD LAYOUT

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



# DGK0008A



# PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

**NOTES:**

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

# EXAMPLE BOARD LAYOUT

DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

# EXAMPLE STENCIL DESIGN

DGK0008A

<sup>TM</sup> VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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